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(12) **United States Design Patent**
Li

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(54) **COVER OF AN ELECTRONIC DEVICE HAVING SURFACE ORNAMENTATION**

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(**) Term: **14 Years**

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(51) **LOC (10) Cl.** **14-03**

(52) **U.S. Cl.**
USPC **D14/248**

(58) **Field of Classification Search**
USPC ...... D14/138 AA, 138 AB, 138 AC, 138 AD, D14/138 G, 138 R, 140, 168, 169, 172, 203, D14/217, 218, 238.1, 240, 247, 248, 250, D14/251, 253, 341, 342, 344, 345, 346, 347, D14/439, 440, 496; D5/46, 53, 56, 58, 99; D3/201, 248, 269, 273, 301, 303; 206/320; 355/29; D25/142, 156; D21/349, 365, 478; 359/514, 529, 530; 428/156
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a cover of an electronic device having surface ornamentation, as shown and described.

DESCRIPTION

The present application is related to co-pending U.S. patent applications Ser. No. 29/418,361, 29/418,363, 29/418,364, 29/418,365, 29/418,368, 29/418,370, 29/418,371, 29/418,373, 29/418,375, and 29/418,377, each, entitled "Cover of an Electronic Device Having Surface Ornamentation", by Bin Li. These applications have the same assignee as the present application and have been concurrently filed herewith. The above-identified applications are incorporated herein by reference.

FIG. **1** is a perspective view of a cover of an electronic device having surface ornamentation showing my new design;

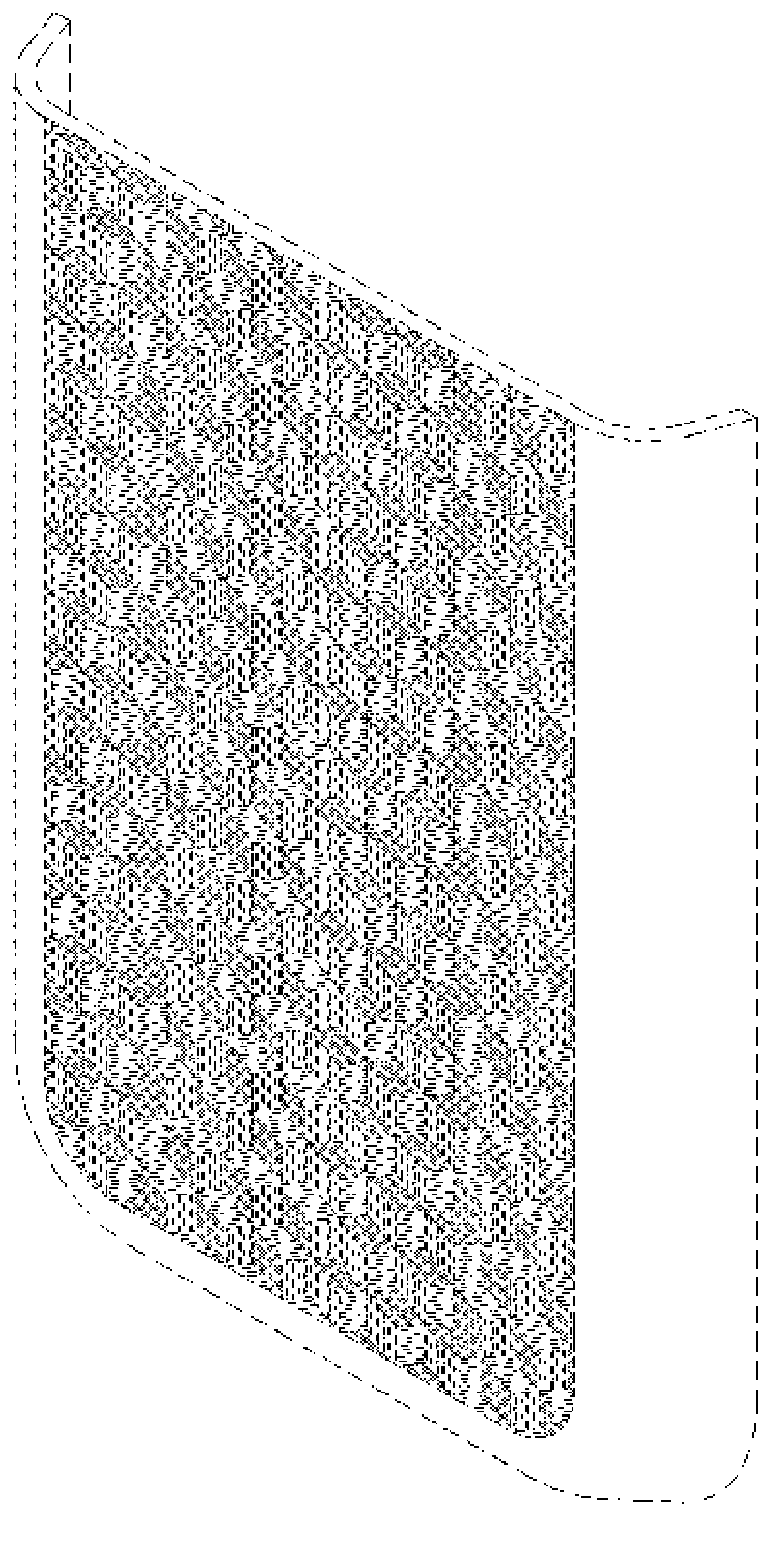
FIG. **2** is a front elevational view thereof;

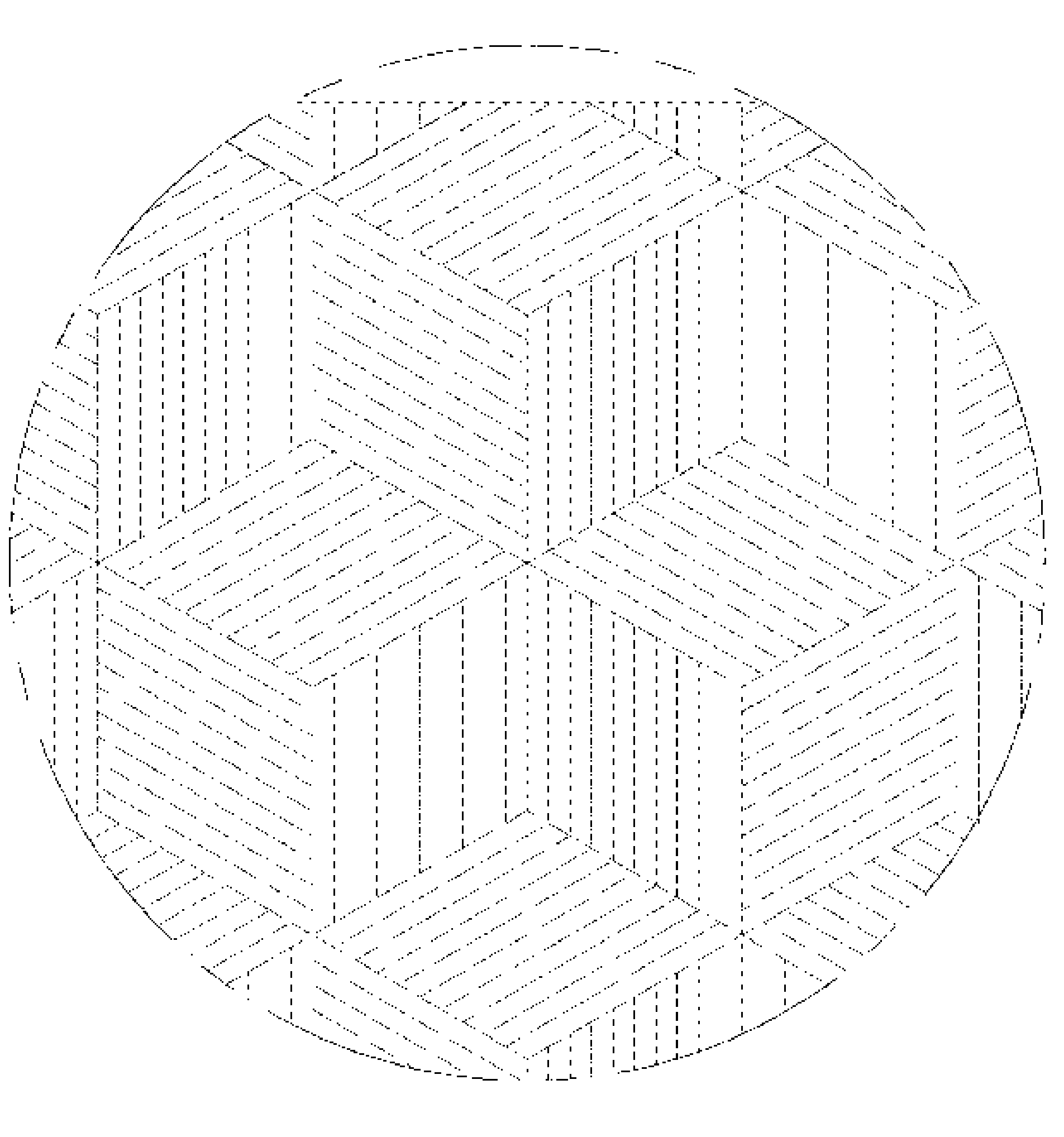
FIG. **3** is a side elevational view thereof; and,

FIG. **4** is an enlarged fragmentary view thereof showing circled portion **4** in FIG. **2**.

In FIG. **1**-**3**, the evenly segmented broken lines indicate portions of the cover of an electronic device having surface ornamentation that form no part of the claimed design. In FIGS. **2** and **4**, the unevenly segmented broken lines indicate the portion of the design that is shown on an enlarged scale in FIG. **4**. The broken lines form no part of the claimed design.

1 Claim, 4 Drawing Sheets





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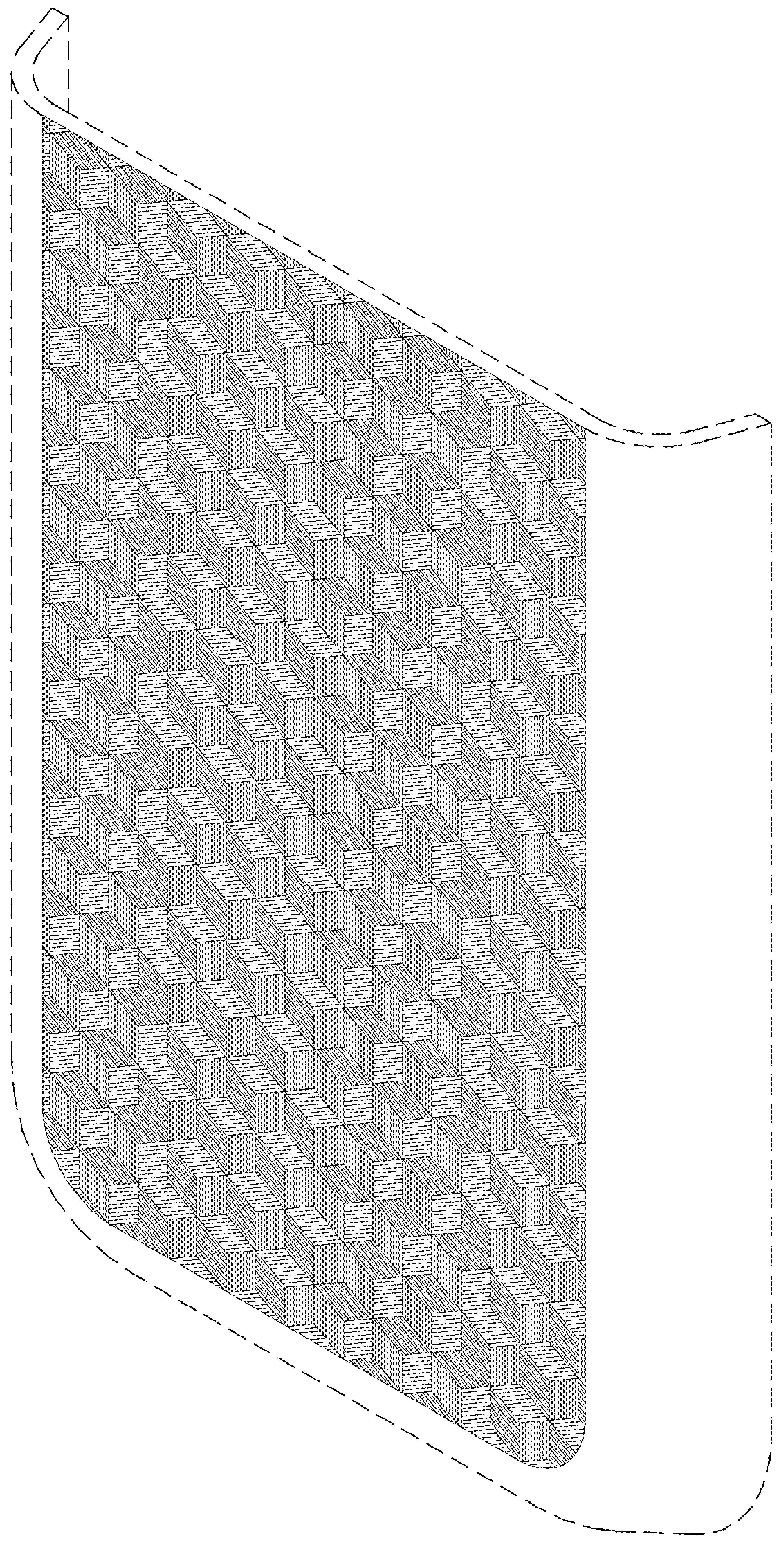

FIG. 1

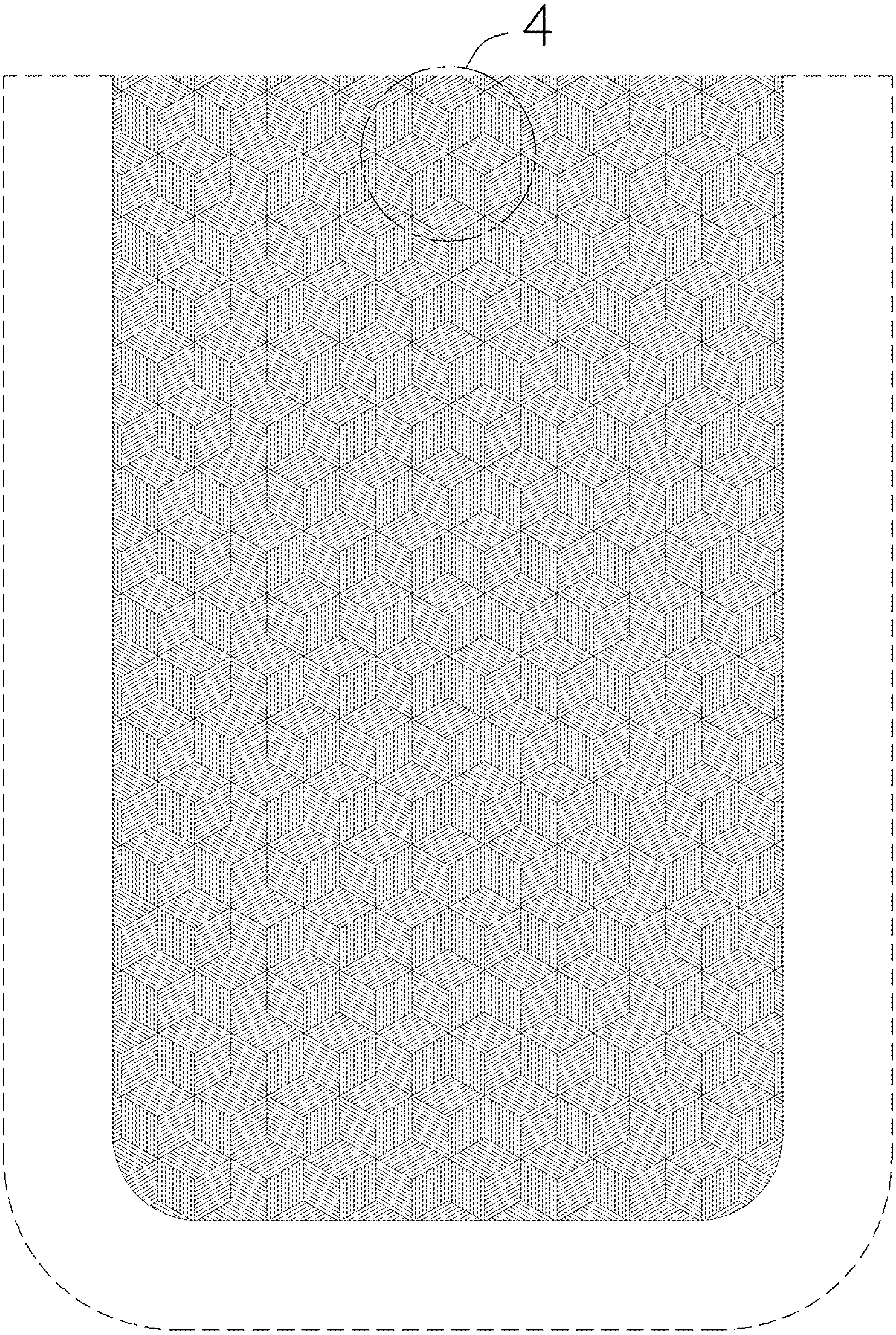

FIG. 2

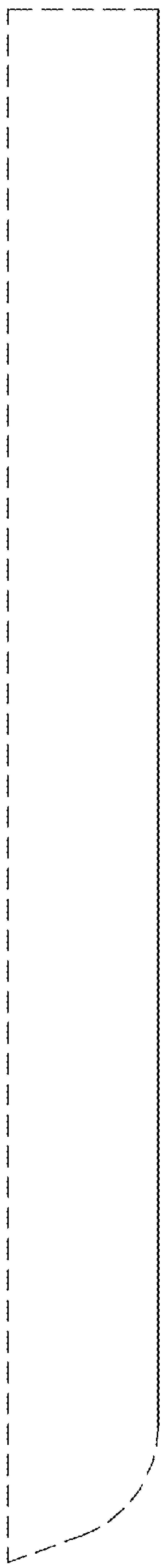

FIG. 3

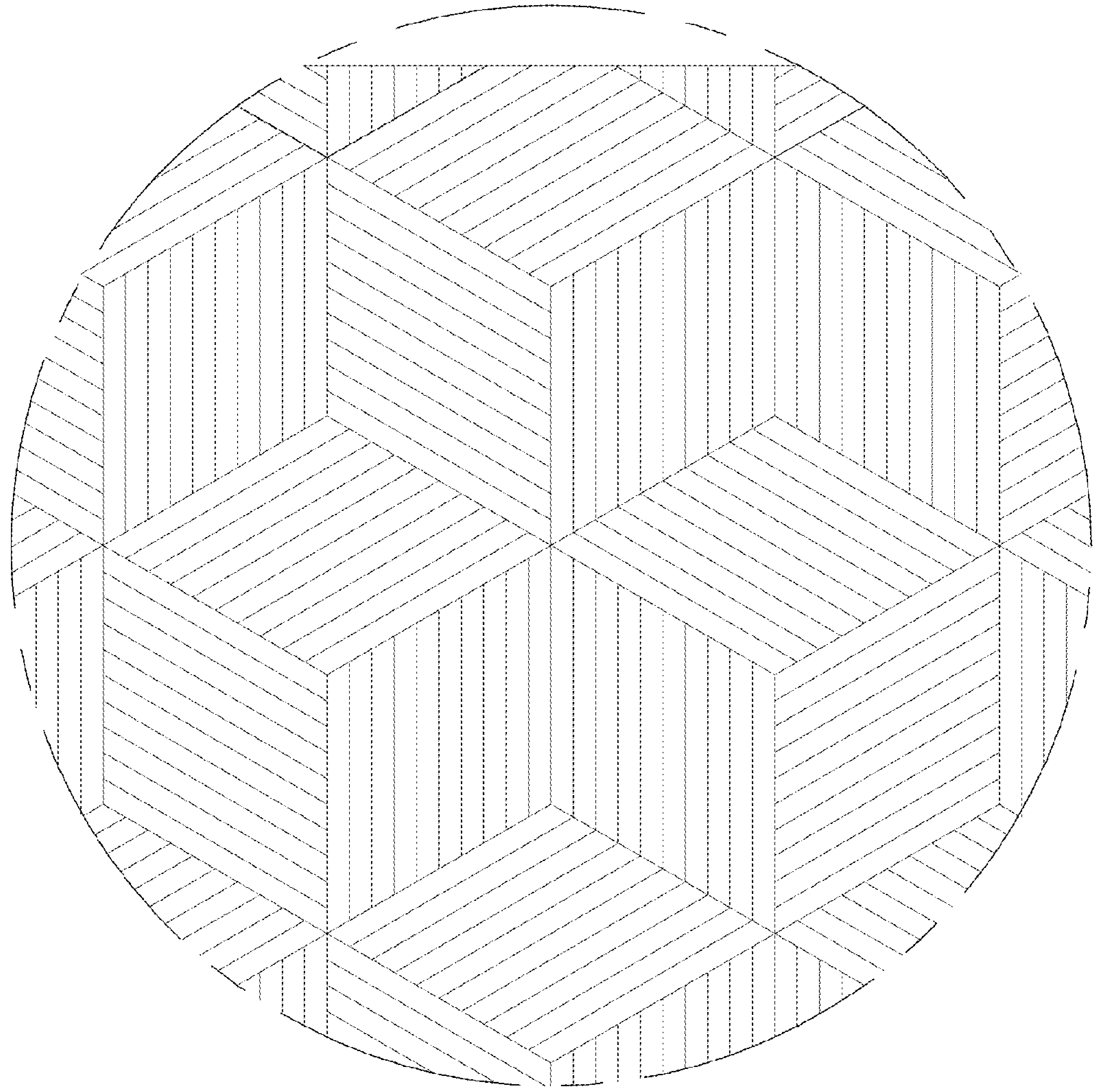

FIG. 4